

October 15, 2002

## **eTeraView**

The e-newsletter of Teradyne's Assembly Test Division

Because Technology Never Stops.

### **NEWS AND ANNOUNCEMENTS**

#### **Teradyne and MetricStream Announce Strategic Alliance; Links Manufacturing Execution with Enterprise Quality Management**

This significant alliance addresses the supply chain execution and quality management needs of the aerospace and defense, automotive, and electronics industries. It provides manufacturers with a powerful combination of tools and services to substantially improve the efficiency of critical manufacturing execution and enterprise quality processes, reducing a manufacturer's costs of goods sold and improving profitability. Click here for further information:

[http://www.teradyne.com/prods/cbt/news/newsdesk/65news\\_pr\\_020917.html](http://www.teradyne.com/prods/cbt/news/newsdesk/65news_pr_020917.html)

#### **Teradyne Expands Relationship with Test Solutions Ltd.**

As one of Teradyne's authorized representatives in Europe, Test Solutions Ltd. (TSL) has responsibility for sales and service for the full range of Teradyne's Test and Inspection solutions exclusively in the U.K. and Ireland. To read more about TSL's association with Teradyne, click here:

[http://www.teradyne.com/prods/cbt/news/newsdesk/66news\\_pr\\_020924.html](http://www.teradyne.com/prods/cbt/news/newsdesk/66news_pr_020924.html)

#### **Teradyne Introduces Bi4-Series™; Industry's First "Synthetic" Bus Test Instrument**

Teradyne introduced the Bi4-Series of serial bus test instruments to the public at the AUTOTESTCON conference focused on automated test and related technology for military, government and aerospace applications. Click here for more information:

[http://www.teradyne.com/prods/cbt/news/newsdesk/67news\\_pr\\_021010.html](http://www.teradyne.com/prods/cbt/news/newsdesk/67news_pr_021010.html)

### **PRODUCT INFORMATION**

#### **TestStudio™ ATE Operating Environment – Constructing Diagnostic Test Programs Has Never Been Easier**

TestStudio, the industry's first open-architecture, web-based ATE Operating Environment provides a flexible and powerful solution for managing the entire test process – from development and documentation through execution and debug. It is the all-in-one solution for the Teradyne Spectrum 9100-Series Functional Tester as well as test system integrators who configure any special purpose PC-driven automatic test equipment. Click here for more information on TestStudio:

[http://www.teradyne.com/prods/cbt/products/test-soft/tststud/tststud\\_ov.html](http://www.teradyne.com/prods/cbt/products/test-soft/tststud/tststud_ov.html)

#### **Bi4-Series of Serial Bus Test Instruments Now Available**

Teradyne's Bi4-Series of serial bus test instruments (BTI) is the industry's "first synthetic" instrument designed specifically to address the unique requirements for real-time bus test and emulation at functional test. The Bi4-Series is capable of assuming a wide range of serial bus protocols required in military and aerospace test environments. To read more about capabilities of the Bi4-Series Instruments, click here:

[http://www.teradyne.com/prods/cbt/products/test-instr/bi4s/bi4\\_ov.html](http://www.teradyne.com/prods/cbt/products/test-instr/bi4s/bi4_ov.html)

## RECENT TECHNICAL PAPERS, ARTICLES, & PUBLICATIONS

### **“Pilot Adds to Service Flexibility” – Teradyne Global Case Study**

Contract test house and manufacturing services provider, Swaptronics, says that there is a great diversity of products currently being built in Western Europe. In contrast to the requirements of high-volume manufacturing, which is currently intent on cutting its overhead to the bone, the ability to successfully service lower-volume customers depends on fast response, a high degree of flexibility, and the ability to conceive and execute adequate test coverage for extremely complex products. To read about a solution that has helped Swaptronics achieve their goals, click here:

[http://www.teradyne.com/prods/cbt/products/library/pilot/cs\\_swaptronics.pdf](http://www.teradyne.com/prods/cbt/products/library/pilot/cs_swaptronics.pdf)

### **“Step by Step – Step 8: Test/Inspection” by Michael J. Smith**

Many types of defects can be found on today's modern printed circuit boards (PBC). The types of defects and the techniques used to inspect them change constantly. Increasing data and clock speeds will reduce in-circuit test (ICT) bed-of-nails access and, therefore, require an increased use of different and complementary inspection strategies. To learn more about this topic, click here:

[http://teradyne.com/prods/cbt/products/library/general/smith\\_smt0209.pdf](http://teradyne.com/prods/cbt/products/library/general/smith_smt0209.pdf)

### **“Teradyne Pushes for Overall Test Solution” by Mario Pereira**

Scalability and reuse are buzzwords in the electronics industry as companies strive to make the most of limited resources in today's economy. Manufacturers are looking at total solutions and are focusing on total costs and cycle time. To read more about this topic, click here:

[http://www.teradyne.com/prods/cbt/products/library/general/tong\\_eet-asia.pdf](http://www.teradyne.com/prods/cbt/products/library/general/tong_eet-asia.pdf)

## UPCOMING EVENTS

### **AUTOTESTCON 2002, Huntsville, Alabama, October 14-17, 2002**

“The New Millennium Challenge – Transforming Test” will reflect the conference's direction to build on past AUTOTESTCON integrated diagnostic technology. Visit Teradyne at booth #906. Click here to read more about this event:

<http://www.teradyne.com/prods/cbt/news/tradeshows/autotestcon02.html>

### **Ottawa Test Engineering Workshop, Ottawa, Ontario, Canada, October 21-23, 2002 (organized by Alcatel Canada)**

The theme of this year's workshop is “Reducing the Cost of Test”. This workshop will allow attendees to share best practices and lessons-learned in test cost-reduction techniques. For more information about this event, click here:

<http://www.teradyne.com/prods/cbt/news/tradeshows/02ottawa.html>

### **Teradyne Users' Group (TUG) – \*\*\* CALL FOR PAPERS \*\*\***

The TUG Steering Committee is looking for papers from you for our next conference, which will be held at the Gaylord Opryland Hotel in Nashville, Tennessee, May 5-7, 2003. **The deadline for abstracts is November 22!** For complete details on the Call for Papers, click here:

<http://www.teradyne.com/prods/tug/t03cfp.html>

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[http://www.teradyne.com/prods/cbt/news/news\\_pubs.html](http://www.teradyne.com/prods/cbt/news/news_pubs.html)

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